

STACKED IC

ABSTRACT OF THE DISCLOSURE

A stacked IC includes a first IC package unit, a second IC package unit and an interface layer. The first IC package unit includes an IC chip, an encapsulant resin and a plurality of lead wires. The IC chip is encapsulated by the encapsulant resin. Each of the lead wires includes a first end connected to the IC chip and encapsulated by the encapsulant resin, a second end extending outside the encapsulant resin, and a bend portion arranged between the first end and the second end and having at least one surface exposed outside of the encapsulant resin. The second IC package unit has the same structure as the first IC package unit. The interface layer is sandwiched between the first IC package unit and the second IC package unit, and has a first side connected to the bend portion of the first IC package unit and a second side connected to the second end of the second IC package unit.